

ABSTRACT

To prepare an adhesive which has excellent heat resistance, suppresses the formation of bubbles during curing
5 and is free from such a defect as opacity caused by the bubbles.

The adhesive composition comprises (A) an organopolysiloxane having two alkenyl groups with 4 or less carbon atoms bonded to silicon atoms in one molecule and a molecular weight of 1,000 or more, (B) an
10 organohydrogenpolysiloxane having at least two hydrogen atoms bonded to silicone atoms in one molecule and a molecular weight of 1,000 or more, (C) a platinum-based catalyst, and (D) an organic silicon compound having at least three alkenyl groups with 4 or less carbon atoms bonded to silicon atoms in one
15 molecule and a molecular weight of less than 1,000 or an organic cyclic silicon compound having at least three hydrogen atoms bonded to silicon atoms in one molecule and a molecular weight of less than 1,200.